

Planar

Electroless Nickel Immersion Gold

Reliability And Stability From A Single High Yield ENIG Plating Process

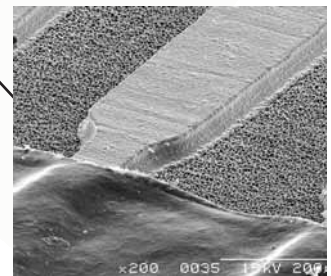
MacDermid Planar is the electroless nickel immersion gold plating process designed specifically to increase yields through the elimination of extraneous and skip plating, while minimizing the risk of black pad. Favored by fabricators, assemblers, and OEM's because of its stability and reliability, Planar is the choice for critical end-use applications.

Planar's patented catalyst systems are what separate Planar from the competition. They selectively metallize copper surfaces only; this directly eliminates both extraneous and skip plating. Formulated by the industry experts in black pad elimination, its high performance nickel phosphorous structure resists corrosion and is exceptionally compatible with soldermasks. Combined with our full range of electroless nickel products, Planar provides a durable, extremely flat deposit ideal for fine pitch SMT, BGA and direct-chip attach assembly.

When reliability, stability and high yield are critical, count on the company that says "Yes We Can." MacDermid.

Key Features

- No plating on laminate or solder masks
- No skip plating
- Nickel structure that resists corrosion
- Patented technology to overcome harmful solder mask effects
- Formulated to prevent black pad
- Excellent solderability, contact resistance and wire bondability
- Simplified bath control



YES WE CANSM

MacDermid
Electronics Solutions

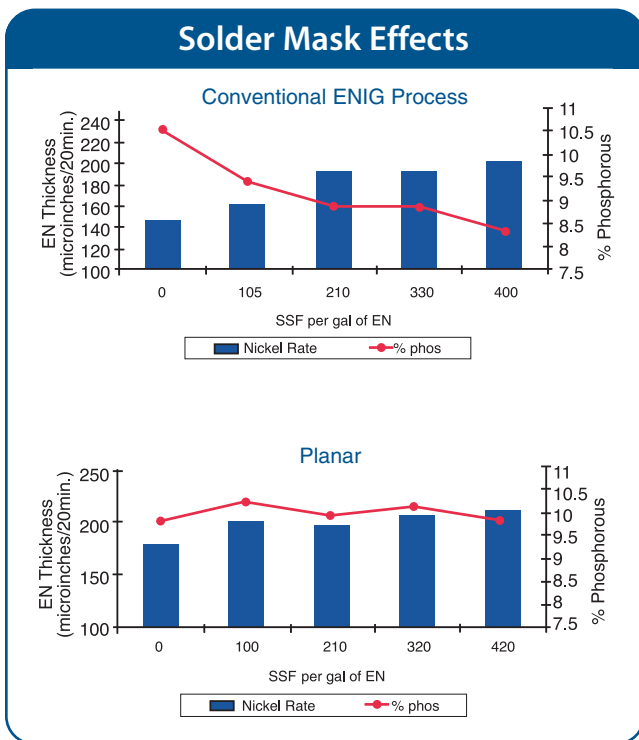
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Planar: From The Leader In Final Finishes

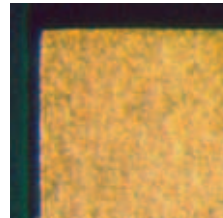
For more than 10 years, MacDermid has been a leader in electroless nickel immersion gold. And when it comes to reliability, stability, and high yield from a single ENIG plating process, look no further than **MacDermid Planar**.

Specified by fabricators, assemblers, and OEM's worldwide, Planar is a superior HASL alternative designed specifically to minimize the mechanisms that can lead to black pad while reducing extraneous and skip plating. Reduce failure rates throughout the entire process with Planar, from the leader in final finishes.

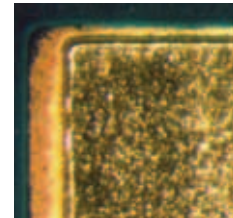


Planar is formulated to deliver consistent performance throughout its extended bath life. With conventional processes, solder mask materials leach into the nickel bath chemistry, resulting in increased nickel rates and reduced phosphorus content. Planar is formulated to prohibit this effect, improving bath stability and minimizing black pad risk.

Stop Extraneous Plating...

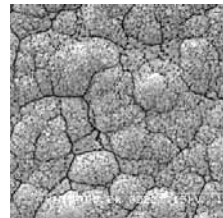


Planar's patented activation systems assure nickel gold plating only where you want it.

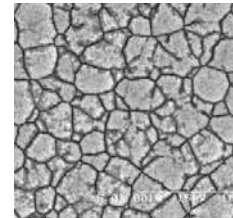


Conventional systems can result in catalyst adsorption in unwanted areas, resulting in extraneous plating.

Guard Against Black Pad...



Planar's corrosion resistance directly prevents black pad.



Cyanide stripping of standard ENIG shows "cracked earth" appearance.

YES WE CANSM

It takes more than innovative, high performance products and superior technical service to help our customers compete and win in today's global marketplace. It takes a total commitment to understanding their needs and the ability to provide the right solutions—every time.

When success is your only goal, trust the company that says "Yes We Can."

 **MacDermid**
Electronics Solutions

For more information, please contact us at:
245 Freight Street, Waterbury, CT 06702 USA
Phone: +1 203.575.5700
www.macdermid.com/electronics